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(54) Title: ABRASIVE MATERIAL FOR THE NEEDLE POINT OF A PROBE CARD

(57) Abstract

An abrasive material for the needle point of a probe card which can effectively remove foreign matter adhering to the needle point of the probe, protect the needle point from damage and deformation, and prolong the life of the probe. The abrasive material for the needle point of a probe card comprises an abrasive layer including a layer of micro-powdered abrasive grains applied to a substrate and a cushion layer having a buffer action and elasticity.

